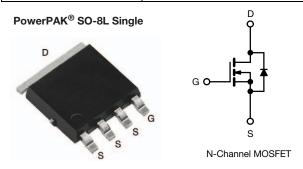
Vishay Siliconix

# **E Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700	)		
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.520		
Q <sub>g</sub> max. (nC)	44			
Q <sub>gs</sub> (nC)	6			
Q <sub>gd</sub> (nC)	9			
Configuration	Sing	le		



#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

# RoHS COMPLIANT HALOGEN FREE

### **APPLICATIONS**

- Switch mode power supplies (SMPS)
- Flyback converter
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Consumer
  - Wall adaptors

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SiHJ7N65E-T1-GE3

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	650	.,	
Gate-Source Voltage			$V_{GS}$	± 30	- V	
Continuous Drain Current /T 150 °C\	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		7.9		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	I <sub>D</sub>	5.0	Α	
Pulsed Drain Current a			I <sub>DM</sub>	17		
Linear Derating Factor				0.77	W/°C	
Single Pulse Avalanche Energy b			E <sub>AS</sub>	68	mJ	
Maximum Power Dissipation			$P_{D}$	96	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope T <sub>J</sub> = 125 °C			4).//d+	70	1//20	
Reverse Diode dV/dt d			dV/dt	14	V/ns	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 120 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 2.2 A.
- c.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R <sub>thJA</sub>	52	65	°C/W
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	1.0	1.3	C/ VV



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PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	650	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.8	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
Cata Saurea Laglana	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-Source Leakage		,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA
Zero Gate Voltage Drain Current	I	V <sub>DS</sub> =	650 V, V <sub>GS</sub> = 0 V	-	-	1	μA
Zero Gate Voltage Drain Gurrent	I <sub>DSS</sub>	$V_{DS} = 520 \text{ V}$	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μΑ
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 3.5 A	-	0.520	0.598	Ω
Forward Transconductance	9fs	V <sub>DS</sub> =	= 30 V, I <sub>D</sub> = 3.5 A	-	2.3	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V,		-	820	-	pF
Output Capacitance	C <sub>oss</sub>	,	$V_{DS} = 100 V$ ,		48	-	
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		-	4	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>			-	33	-	
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>	V <sub>DS</sub> = 0 \	/ to 520 V, V <sub>GS</sub> = 0 V	-	118	-	
Total Gate Charge	$Q_g$			-	22	44	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 3.5 \text{ A}, V_{DS} = 520 \text{ V}$	-	6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			-	9	-	
Turn-On Delay Time	t <sub>d(on)</sub>			-	16	32	
Rise Time	t <sub>r</sub>	$V_{DD} =$	520 V, I <sub>D</sub> = 3.5 A,	-	18	36	
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$=$ 10 V, R <sub>g</sub> = 9.1 $\Omega$	-	30	60	ns
Fall Time	t <sub>f</sub>			-	18	36	
Gate Input Resistance	R <sub>g</sub>		f = 1 MHz	0.4	0.8	1.6	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET sym showing the	MOSFET symbol showing the		-	7.9	
Pulsed Diode Forward Current	I <sub>SM</sub>	integral revers p - n junction		-	-	17	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	S, I <sub>S</sub> = 3.5 A, V <sub>GS</sub> = 0 V	-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	-		-	299	598	ns
Reverse Recovery Charge	Q <sub>rr</sub>	$T_J = 25$	5 °C, I <sub>F</sub> = I <sub>S</sub> = 3.5 A, 100 A/μs <sup>, V</sup> <sub>B</sub> = 25 V	-	2.9	5.8	μC
Reverse Recovery Current	I <sub>RRM</sub>	ui/at =	100 A/µS, 'R = 20 V	-	16	-	A

### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



# TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

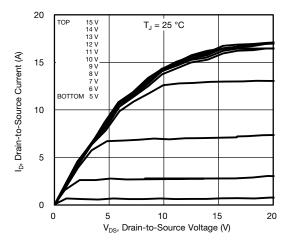


Fig. 1 - Typical Output Characteristics

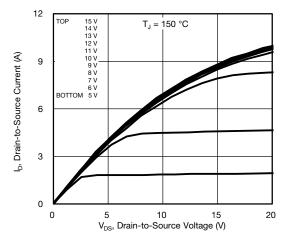


Fig. 2 - Typical Output Characteristics

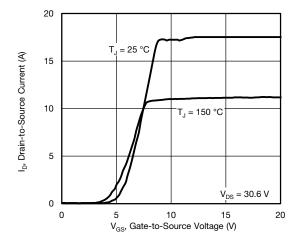


Fig. 3 - Typical Transfer Characteristics

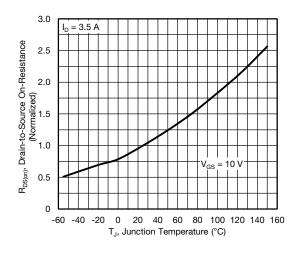


Fig. 4 - Normalized On-Resistance vs. Temperature

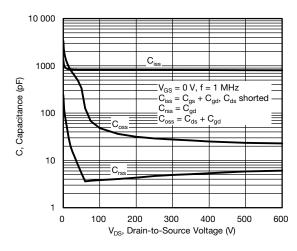


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

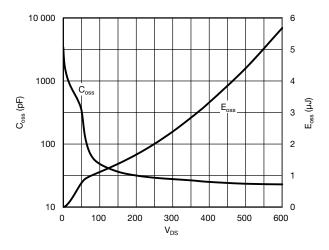


Fig. 6 - Coss and Eoss vs. VDS



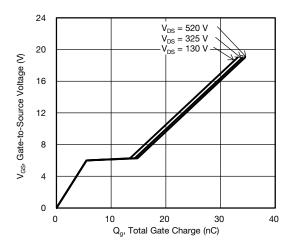


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

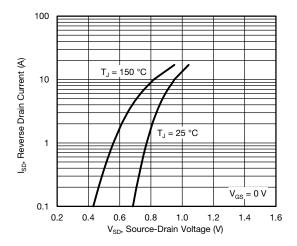


Fig. 8 - Typical Source-Drain Diode Forward Voltage

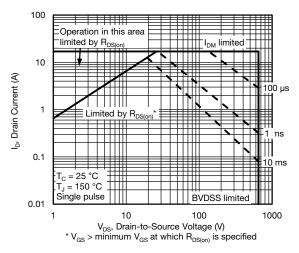


Fig. 9 - Maximum Safe Operating Area

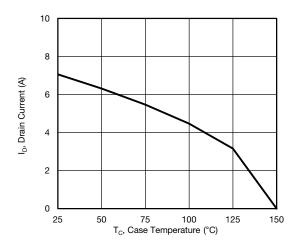


Fig. 10 - Maximum Drain Current vs. Case Temperature

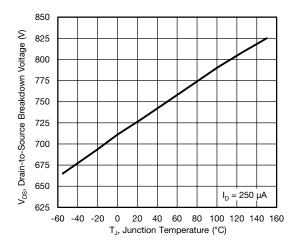


Fig. 11 - Temperature vs. Drain-to-Source Voltage



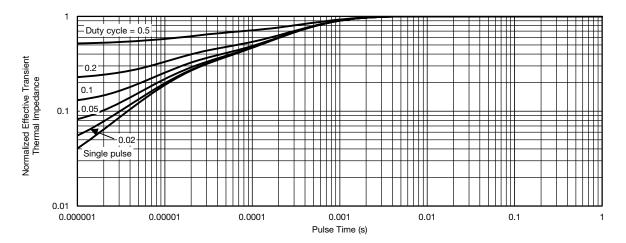


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

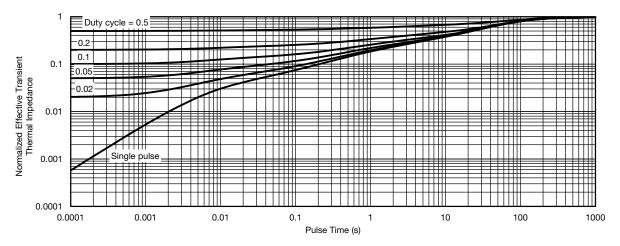


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

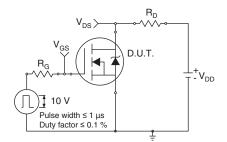


Fig. 14 - Switching Time Test Circuit

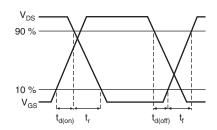


Fig. 15 - Switching Time Waveforms



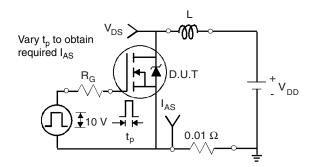


Fig. 16 - Unclamped Inductive Test Circuit

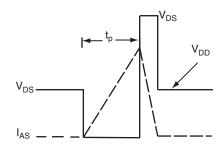


Fig. 17 - Unclamped Inductive Waveforms

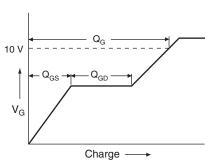


Fig. 18 - Basic Gate Charge Waveform

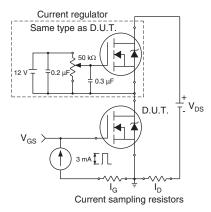
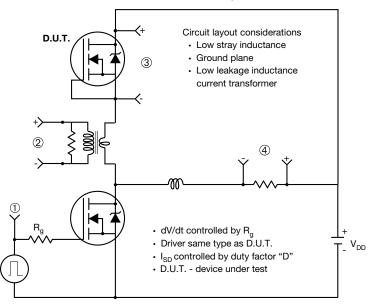


Fig. 19 - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



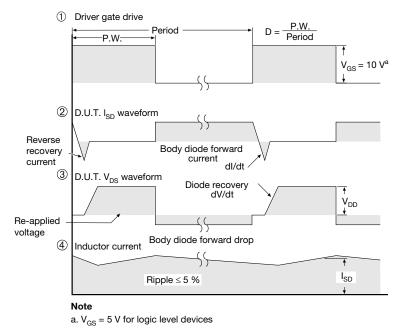
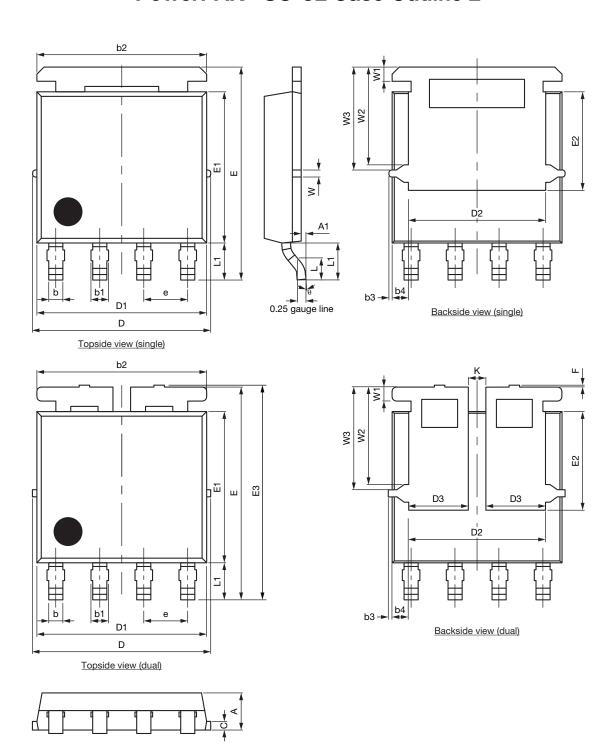


Fig. 20 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?91823">www.vishay.com/ppg?91823</a>.



# PowerPAK® SO-8L Case Outline 2





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DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX	
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
E3	6.05	6.22	6.40	0.238	0.245	0.252	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W	0.23			0.009			
W1	0.41			0.016			
W2	2.82			0.111			
W3	2.96			0.117			
θ	0°	-	10°	0°	-	10°	

DWG: 6044

#### Note

• Millimeters will govern



## RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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Vishay

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